

**Supply, Installation, Testing, Commissioning
and Training of Network Devices
(Layer-3 Switches and Layer-2 Switches)**



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1. INTRODUCTION

STPI invites Tender under Two Bid Systems (Technical Bid & Commercial Bid) for Supply, Installation, Testing, Commissioning and Training of Network Devices - LAYER-3 Switches and LAYER-2 Switches at various STPI Locations as mentioned in the Annexure- A , as per the scope of works in part -1 b and Technical specifications in part -1c of . The summary of Networking Devices proposed for procurement across STPI center is as per Table A below:

Table A

Layer-3 Switch 48 Port	Layer-2 Switch 24 Port	Total
75	56	131

2. BID SUBMISSION

STPI invites Two Bid Systems (Technical Bid & Commercial Bid) for Supply, Installation, Testing, Commissioning and training of Network Devices at various STPI Locations as mentioned in the **Annexure-A**.

Part I shall comprise the following documents:

Part I-A – General Terms and Conditions of the tender

Part I-B – Scope of Works

Part I-C – Technical Specification

Part I-D – Annexures and formats

Part II shall be the price offer to be submitted separately as per the format in Annexure-BOQ. The price offer will be considered only of those parties who submitted all documents indicated in the checklist at **Part I** of the tender document and are found competent on the basis of information submitted in **Part I**.

Bidders are requested to submit their most competitive rates. It may please be noted that incomplete bids will NOT be accepted.

I. **Contents of Technical Bid:** The bidder shall upload the scanned copy of all the following documents as part of the Technical Bid in the stipulated format.

- a) Copy of Registration / Incorporation of the firm/ company as applicable.
- b) Copy of the PAN Card, GST, MSME/UAM Registration (if applicable)
- c) Earnest Money Deposit/Bid Security Declaration
- d) OEM(s) Authorization Certificate and OEM(s)/ Manufacturers Authorization Form(s)/Certificate (MAF) authorizing the bidder to participate in the referred tender.
- e) **Financial status:** CA certificate for the Annual turnover of the bidder in the last three years, Copy of the Audited Financial Statement for the past 3 financial years. (2021-22, 2022-23, 2023-24)
- f) **Experience Proof:** Customer's Purchase Order (PO) & copy of Invoice and completion certificate indicating the proof of having successfully completed /supplied and installed similar products to its customers during the last three financial years (2021-22,2022-23 and 2023-24).
- g) Documentary proof w.r.t registration of OEM and the OEM products for the proposed products in the Trusted Telecom Portal as per DoT Guidelines.
- h) Documentary evidence for having a support center in at least 4 major cities across India, along with a trouble call escalation matrix to be submitted.
- i) Product Datasheets, Brochures of the proposed products, etc.
- j) Compliance to Technical Specifications as in Part-1c
- k) Declaration from OEM w.r.t product warranty, End of Life, End of Support, etc as per RFP terms.
- l) Duly filled and signed Technical Compliance Sheet as per **Annexure-B** in part I-D ("Tech-Compliance")
- m) Duly filled (and signed) details of proposed product as per **Annexure-C** in part I-D (Components and Products).

- n) Acceptance to training terms as per **Annexure-D** in part I-D (Training Requirement).
- o) Duly filled and signed checklist as per **Annexure-E** in part I-D
- p) Duly filled and signed Tender acceptance Letter as per **Annexure-F** in part I-D
- q) Bidders shall not be under a declaration of ineligibility for corrupt and fraudulent practices. The declaration for non-debarment & non-blacklisting has to be submitted as per format specified in **Annexure-G**
- r) NDA as per **Annexure -H** in part I-D.
- s) No subcontracting is allowed. Declaration attested by the authorized signatory on the company letterhead.
- t) Acceptance of the **Scope of work as per the bid document at Part I-B**. Self-attested and signed scope of works document to be submitted.
- u) Acceptance of the **payment terms, penalty and liquidated damages (LD) as per the bid document at Part I-B**.
- v) Certificate of Conformity/ No Deviation. Compliance needs to be provided on letterhead as per the format at **Annexure -I** to be submitted.
- w) Board Resolution or Power of Attorney for the Authorised Signatory shall be submitted as per as per format at **Annexure -J**.
- x) EMD / Bid security Declaration as per format at **Annexure -K**.
- y) Declaration from MSME vendor for declaration of UAM numbers with GeM portal.
- z) Vulnerability Assessment and Penetration Testing (VAPT) Report of the quoted products
- aa) Any other related supporting documents.

II. Contents of Price Bid:

The price bid is as per the Annexure-BOQ format, filled BOQ shall be uploaded by the bidders in the GEM portal.

- III. Bidders shall not be under a declaration of ineligibility for corrupt and fraudulent practices. The declaration is to be submitted by the bidders as per format specified in **Annexure-G**.
- IV. STPI reserves the right to cancel/withdraw the bid without assigning any reasons for such a decision. Such a decision will not incur any liability whatsoever on the part of STPI.
- V. Bidders shall adhere to the procedure and processes laid down in this document and shall follow fair and ethical practices of trade.

VI. Deadline for Submission of Bids

- a. Bids must be submitted online within the due time, date specified in the tender.
- b. STPI may extend this deadline for submission of bids by amending the bid documents. This will be suitably notified on the websites www.stpi.in and <https://gem.gov.in/>

VII. STPI reserves the right to accept the offer in full or in parts or reject it summarily.

VIII. Comparison of Bids: STPI will compare the bids from the short-listed bidders.

- IX. The bidding process is stipulated in the tender document clearly. In case of any clarifications about the bidding process/eligibility criteria, the bidders may seek clarification during the pre-bid meeting or through GeM Portal in prior to the pre-bid meeting. The clarifications sought after the pre-bid meeting will not be entertained.
- X. The award of contract shall be hosted on the website www.stpi.in/ & <https://gem.gov.in/> . The reason for non-selection shall be disclosed on bidder written requests for the same.
- XI. STPI reserves the right to increase/decrease the quantity of said Networking devices by 25%, as per GeM terms, during the execution & the successful bidder shall supply the additional quantity at the quoted unit prices.

3. PART I-A: GENERAL TERMS AND CONDITIONS OF TENDER

- I. The tender should be submitted online only on <https://gem.gov.in/>
- II. Quotations shall be submitted for Supply, Installation, Testing, Commissioning and Training of Layer-3 Switches and Layer-2 Switches with Product Warranty for a minimum period of 5 years.
 - a. Bid validity: The tender submitted should be valid for 180 days from the date of opening of the bid.
 - b. STPI may ask for the bidder's consent to extend the period of validity. Such a request and the response shall be made in writing only. The bidder is free not to accept such a request without forfeiting the EMD. A bidder agreeing to the request for extension will not be permitted to modify their bid.
- III. Only net rates with break-up shall be quoted for the period of the arrangement. Tenderers/bidders are advised to exercise the greatest care in offering the rates.
- IV. Earnest Money Deposit (EMD)
 - a. EMD / Bid security for an amount of Rs. 10,00,000/- (Rupees Ten Lakhs only) in the form of RTGS/NEFT, in favour of STPI, payable at New Delhi has to be submitted along with the bid. Bank details mentioned below: -

Bank Name-Canara Bank
Account No.-1098101101244
IFS Code-CNRB0001098

- b. The Copy of EMD/Bid Security Declaration should be submitted along with the bid document, within the bid submission date and time of the tender, failing which the offer will be liable for rejection.
- c. EMD will not be accepted in the form of cash/cheque. No interest is payable on EMD.
- d. The EMD will be returned to the bidder whose offer is not accepted by STPI.
- e. The bidder whose offer is accepted, the EMD will be returned on submission of the PBG of 10% of the total PO value.
- f. The PBG will be valid till the warranty period, i.e. 5 years plus 60 days.
- g. However, if the return of EMD is delayed for any reason, no interest/penalty shall be payable to the bidder.
- h. The successful bidder, on award of contract/order, must send the contract/order acceptance in writing, within 7 working days of award of contract/order, failing which the EMD will be forfeited.
- i. The EMD shall be forfeited if the bidder withdraws the bid during the period of bid validity specified in the tender.
- j. The following categories of bidders shall, however, be exempted from furnishing EMD/Bid Security:
 - i) Micro and Small Enterprises (MSEs) who are holding valid Udyam Registration and are manufacturers of the offered Product or Service (Primary Product / Service - in case of bunch bid with total valuwise evaluation) and give specific

confirmation to this effect at the time of bid submission and claim EMD exemption and whose credentials are validated online through Udyam Registration website of Ministry of MSME and also through supporting document uploaded during bidding process and validated by the purchaser.

- ii) Start-ups as recognized by the Department for Promotion of Industry and Internal Trade (DPIIT), holding a valid Startup Recognition Certificate, which is to be uploaded while bidding and claiming EMD exemption and to be validated by the Buyer. Bidder to ensure that turnover for any of the financial years has not exceeded the limits prescribed in the certificate / Start-Up scheme of DPIIT.
- iii) Sellers / Service Provider having an annual turnover of ₹ 500 Crore or more, at least in one of the past three completed financial year (s).
- iv) Central / State PSUs.

k. Bidders who are exempted from furnishing bid security as per the above clause are required to furnish a bid security declaration as per the format given at **Annexure -K**.

V. PERFORMANCE SECURITY:

- a) The successful bidder shall furnish performance security to the purchaser for an amount equal to 10% of the Purchase Order value within 14 days from the date of issue of the Purchase Order by the Purchaser.
- b) The security performance shall be in the form of a Bank Guarantee issued by a Nationalised/Scheduled Bank and in the form provided in Annexure-L of this Bid document.
- c) The performance security bond shall be valid for a total period of 5 years + 60 days.
- d) The performance security Bond will be released by the Purchaser after completion of the successful bidder's performance obligations.

VI. The contracts concluded by STPI are subject to the final approval of the Competent Authority, STPI.

VII. Company/Firm blacklisted by Govt./Autonomous Body/PSU/Corporate organisation are not eligible to Bid. If at any stage of the bidding process or during the currency of the contract, such information comes to the knowledge of STPI, the STPI shall have the right to reject the bid and forfeit the bid security or terminate the contract, as the case may be, without any compensation to the bidder.

VIII. Interpretation of the clauses in the Tender Document / Contract Document: In case of any ambiguity/dispute in the interpretation of any of the clauses in this Tender Document, the interpretation of the clauses by the Competent Authority, STPI, shall be final and binding on all parties.

IX. RESOLUTION OF DISPUTES

Any dispute or difference arising out of or in connection with this RFP shall be settled amicably through mutual consultation and negotiation between the Parties in good faith, and by all reasonable and appropriate means. Failing which, the unresolved disputes/issues, as the case may be, between the Parties shall be finally settled by arbitration by a sole arbitrator, appointed by the Parties jointly, and in accordance with the provisions of the Indian Arbitration and Conciliation Act, 1996, and any statutory

modification or amendment thereof, as made from time to time. The language of arbitration shall be English. The seat and venue of arbitration proceedings shall be New Delhi, India, and the arbitral award made in pursuance thereof shall be binding on the Parties.

All documents and communications between the parties shall be in English. However, the expenses incurred by each party in connection with the preparation, presentation shall be borne by the party itself.

X. ELIGIBILITY CRITERIA

#	Eligibility Criteria	Supporting document to be submitted
1.	The Bidder should be legal entity registered in India as a firm/ company /sole proprietorship/ partnership and must be registered with the appropriate authority in India for at least the past 5 years	Copy of Certificate of Registration / Incorporation of the firm/ company.
2	Bidder must have valid PAN, GST, MSME/UAM Registration /statutory compliances as applicable to this tender.	Need to provide a Self-attested photocopy of valid Certificates such as PAN, GST, MSME/UAM Registration
3	The Bidder shall be either an Original Equipment Manufacturer (OEM) or an authorized certified partner of an OEM.	Copy of certificate authorized by OEMs / OEMs certificate and Manufacturer's Authorization Forms (MAFs) from OEM authorizing bidder to participate in the referred tender to be submitted.
4	The bidder/OEM should have support centres in a minimum of 4 major cities across India.	Documentary evidence for having support centers in a minimum of 4 major cities across India, along with a trouble call escalation matrix to be submitted.
6	Financial Turnover: The average annual turnover of the bidder for the last three years should be at least Rs. 2.5 Crore (i.e. 2021-22, 2022-23, 2023-24).	Copy of the Audited balance sheet and IT returns for the past 3 financial years. (2021-22, 2022-23, 2023-24).
7	Project Experience: The bidder should have executed similar projects (such as supply, installation, testing and commissioning of Switches) to the customers in India in the last three financial years (i.e. FY 2021-22, 2022-23 and 2023-24.	Documentary evidence of experience, such as a copy of the Purchase Order, Invoice and completion certificate. • 1 similar completed work order costing not less than Rs. 4 Cr. or • 2 similar completed work orders costing not less than Rs. 2.5 Cr. or • 3 similar completed works orders costing not less than Rs. 2 Cr.

		AND Bidder should have supplied similar products to a minimum of 80% of the proposed quantity as per this RFP. <i>Note: The work order should be issued after 1st April, 2021</i>
8	The proposed products shall be listed in the Trusted Telecom Portal as per DoT Guidelines.	Documentary proof w.r.t registration of OEM and the OEM products for the proposed products in the Trusted Telecom Portal as per DoT Guidelines
9	The bidder shall submit the relevant Documents (i.e. Brochures, Warranty Certificate, Certificate of conformity, Power of Attorney, Copy of EMD/ Bid security Declaration, etc.) w.r.t the proposed products / as per RFP terms.	• Product Datasheets of the proposed product. • Declaration from OEM w.r.t product warranty, End of Life, End of Support, etc, as per RFP terms • Certificate of Conformity/ No Deviation. Compliance needs to be provided on bidder's letterhead (as per format at Annexure -I) • Board Resolution or Power of Attorney for the Authorised Signatory shall be submitted as per the format at Annexure –J • EMD/ Bid security Declaration as per format at Annexure –K • Declaration from MSME vendor for declaration of UAM numbers with the GeM portal • Any other related supporting documents
10	Bidder shall submit the compliance sheet and tender Acceptance form as per the RFP terms	• Compliance to Technical Specifications as in Part-1c • Duly Filled and signed Technical Compliance Sheet as per Annexure-B in part I-D ("Tech-Compliance") • Duly filled (and signed) details of proposed product as per Annexure-C in part I-D (Components and Products). • Duly filled and signed checklist as per Annexure-E in part I-D • Duly filled and signed Tender acceptance Letter as per Annexure-F in part I-D

		NDA as per Annexure –H in part I-D.
11	Bidders should not be under a declaration of ineligibility for corrupt and fraudulent practices.	The declaration for non-debarment & non-blacklisting to be submitted as per format specified in Annexure –G .
12	Acceptance of the Scope of Work and payment terms, penalty and liquidated damages (LD) as per the RFP Terms (i.e. Part I-B)	Self-attested and signed Scope of Works document to be submitted as per Part I-B and acceptance of the payment terms, penalty and liquidated damages (LD) as per the bid document.
13	At the time of bid submission, the proposed product must be audited by CERT-In empanelled security auditing agency for vulnerability assessment and penetration testing	Certificate from the CERT-In empanelled security auditing agency.

Documentary proof of the above shall be submitted. The scanned copy of the document should be uploaded at the time of online submission.

XI. Technical & Financial Evaluation

The bidders who fulfil the minimum eligibility criteria will be considered for Technical Evaluation. The Technical Evaluation process will be based on the Least Cost Based Selection (LCBS) Option. As part of the Technical Evaluation process, the bidders will be assigned the Technical Score against various attributes as per the Table below. The bidders will be called for the technical presentation. The bidders are also required to carry out the Proof of Concept (PoC) / Demonstration of the Technical specifications of all the quoted products as per the RFP.

The bidder is required to score a minimum of **75 marks** to qualify for the Technical Evaluation stage. The financial bids of only the technically qualified bidders will be considered for financial bid evaluation.

The Financial evaluation is based on the lowest evaluated commercial bid (L1). The technically qualified bidder whose bid has been determined as the lowest evaluated commercial bid (L1) will be considered as the Successful bidder.

Table: Technical Scoring

Sl.No	Technical Qualification Criteria	Max Marks	Scoring Method
1.	Relevant Quality Certifications for all quoted products: Common Criteria certification of EAL2/NDPP/MEF 3.0 or its equivalent or above for the proposed Products	5	Common criteria certification of EAL2/NDPP/MEF 3.0 or its equivalent or above for the proposed Products -5 Marks

2.	Financial Turnover: Annual Average turnover of the bidder for the last three years should be at least Rs. 2.5 Crore. Copy of Audited balance sheet and IT returns for the past 3 financial years. (i.e. 2021-22, 2022-23, 2023-24)	20	Average of Annual turnover for prescribed 3 years will be considered and marks will be given as follows: • Rs 2.5 Crore – 10 Crore -10 marks • Rs 10 Crore – 25 Crore -15 marks • Above Rs 25 Crore - 20 marks
3.	Project Experience: The bidder should have executed similar project (such as supply, installation, testing and commissioning of Switches) to any central / State Govt. offices/PSU/ private units in India in last three financial years (i.e. FY 2021-22, 2022-23 and 2023-24)	25	Marks shall be provided for the multiple similar work having deployed IT resources listed in the Resource category: • Total Work / Purchase order value of Rs 4 Cr – Rs 10 Cr: 10 Marks • Total Work / Purchase order value of above Rs 10 Cr – Rs 25 Cr: 15 Marks • Total Work / Purchase order value of above 25 Cr: 20 Marks • From the above Purchase / Work Orders, if any order belongs to central / State Govt. offices / PSU with the value of Rs 10 Cr or above additional Marks shall be awarded: 5 Marks
4.	No. of years in operation	10	• 3 years to 5 years - 5 Marks • 5 years to 10 years -8 Marks • Above 10 years -10 Marks
5.	Presentation by bidder	10	• Bidders' Capabilities: 5 Marks • Overall Project Execution Plan:2.5 Marks • Implementation Schedule/Plan:2.5 Marks
6.	Proof of Concept (PoC) and VAPT	30	POC of the proposed product against the Technical Specifications mentioned in the RFP- 30 Marks

XII. AWARD OF CONTRACT

- STPI shall award the contract to the eligible bidder whose bid has been determined as the lowest evaluated commercial bid (L1).
- Purchase order shall be placed on the successful bidder by STPI as listed at **Annexure–A** for supply of Network devices as listed. However, the invoices will be generated by the bidder as per the place of supply.
- STPI reserves the right to award the contract partly or wholly to one or more bidders.

4. PART I-B: SCOPE OF WORK

- I. The Bidder must supply Network Devices, i.e., LAYER-3 Switches and LAYER-2 Switches in accordance with the specifications mentioned in part I-C. The bidder shall ensure the successful installation, configuration, testing, commissioning and training of LAYER-3 Switches and LAYER-2 Switches in the STPI Directorates and its sub-centers network.
- II. The summary of Network Devices proposed for procurement as per the referred RFP is as per Table A below:

Table A

Layer-3 Switch 48-Port	Layer-2 Switch 24-Port	Total
75	56	131

- III. Proposed Product should be seamlessly integrated with existing STPI Directorate and its sub-centers Heterogeneous Network (i.e. ISP Link Termination, BGP, OSPF, VLAN, STP configurations etc.) which consists of Cisco, Juniper, D-link, Extreme, Huawei Make equipment, failing which STPI have all rights to reject the product and the bid.
- IV. The proposed product should have not been announced for “End of Sale”, “End of Support” and “End of Life” by the respective OEM till the end date of bid submission. Declaration from OEM must be submitted.
- V. Partial bidding is not allowed. The bidder is required to quote for all the Networking Devices listed for the STPI locations.
- VI. **Documentation:** The supplier shall provide the following documents:
 - i. Installation Report
 - ii. Product / user manuals
 - iii. Test Reports
- VII. **Training:** Successful bidder shall provide the training along with the training materials on the proposed product for a minimum of 30 members for a minimum duration of 2 days. The participation certificate is to be issued to the participants. The tentative contents of the training are attached as **Annexure-D** which covers the training requirement of STPI. The exact number of members for training, venue and mode of training will be intimated later.
- VIII. **Warranty Period support:** The successful bidder shall provide Warranty Period Support, including hardware support for a minimum period of 5 years from the date of successful installation and acceptance by respective STPI center. This warranty should cover both parts and onsite support.
 - a) OEM must authenticate the above-mentioned warranty period and the certificate of the same should be produced.
 - b) OEM shall support the proposed product (both hardware and software) for at least 6 years from the date of installation at the respective STPI centre. Declaration from OEM to be submitted.

- c) In case OEM declares End of Support (EoS) before the warranty/Support period, the bidder has to replace the device with product which is compatible, equivalent or better specification without any cost to STPI.

IX. **Service Norms:** The Bidder must follow the Service norms during the warranty period as below:

- a) Response Time: Immediate after call logging (Not more than 30 Minutes).
- b) Resolution Time (for Non-Hardware Related Issues): 4 Hours or Less.
- c) Resolution Time (For Hardware Related Issues): 8 Hours or less
- d) Service Hours: 24/7 Service Support should be provided.
- e) Faulty Hardware Replacement: Next Business Day (NBD) for all STPI Centers.
- f) Support includes hardware, software/firmware and configurations support of the product from OEM.
- g) In case of replacement for faulty spare parts, it should be compatible and of the same make and same model or better specification is with mutual consent without any cost to STPI.
- h) In case delay is beyond the response / resolution time indicated above in repair/replacement of faulty hardware, penalty of 1% of Purchase Order (PO) value of the respective line-item per day up to maximum of 10%.
- i) In case the device is not repairable during the warranty, compatible device of same or equivalent specification of the faulty device is to be provided by the bidder with no cost to STPI.
- j) Based on STPI's requirement, configuration support should be provided w.r.t the proposed products.
- k) In case of Upgradation of firmware is needed, the upgradation should be carried out timely with latest stable version.

X. **Delivery/Execution of order:** Successful bidder shall supply the products/equipment to the referred delivery address within **ten (10) weeks** from the date of issue of Purchase Order to the mentioned delivery address. The installation, configuration, testing and commissioning should be completed by the bidder within **four (4) weeks** upon the supply of products /equipment at site as per the POA provided by STPI. The end-to-end supply, Installation & Commissioning, needs to be completed within 14 weeks of receipt of the Purchase Order. In case of delay, the penalty clause shall be applicable as per prevailing norms. **(1 % of PO cost per week with a maximum of 8 weeks delay)**. Delaying beyond 8 weeks may lead to cancellation of PO, forfeiture of PBG and disallowing of participation in future STPI tenders for a minimum of 1 year. In case the product/Equipment is not complying to the technical specifications as per Part 1-C, the product / Equipment shall be rejected with forfeiture of Performance Security and the necessary information will be circulated to the concerned authorities including NSIC authorities (for the bidders registered with NSIC), disallowing participation of the bidder in future tenders of STPI and others. The items are to be delivered to the STPI locations as per **Annexure-A**.

XI. **Support Centre:** The bidder/OEM shall have support centers at least 4 major cities across India. The bidder should furnish the Escalation matrix including names, locations, complete postal address and telephone numbers of all technical support centers and also alternate contact persons including bidder. Any change in the above details shall have to be intimated in writing by the bidder to STPI at the earliest.

XII. **Payment:** No advance payment will be made. 100% payment will be released after completion of testing, installation, training & submission of warranty certificate.

XIII. **Liquidity Damages:** Purchases/Contracts are subject to Liquidity Damages. Deviation in any of the terms of the PO with due acceptance from STPI will not attract any liquidity damages. The following liquidity damages are levied if there is a delay in the delivery schedule defined in the Purchase Order:

a) Within one week from scheduled delivery and Installation (i.e. 14 weeks) terms - 1% of order value.

b) Every successive week - 1% of order value.

c) Maximum – 8 % of order value for 8 weeks, beyond 8 weeks may lead to cancellation of PO and forfeiture of PBG amount.

d) In case the bidder fails to extend support during the warranty period as per RFP terms, it will lead to forfeiture of balance amount which is due for payment and PBG. Further, the bidder will be debarred from participating in all the ongoing and future procurement tenders across STPI-Centers for a minimum of 1 year period.

XIV. **Non-Disclosure Agreement (NDA)**

The successful bidder has to enter into NDA as per the **Annexure-H**. The NDA shall be submitted along with the acceptance of the Purchase Order.

5. PART I-C: TECHNICAL SPECIFICATION

The models of LAYER-3 switches and LAYER-2 Switches proposed by the bidders shall meet all the specifications mentioned in the table below:

I. Layer-3 Switch	
1	Hardware Architecture / General Description
	a) The Switch should have at least a 48-Port Gigabit Ethernet Interface (10/100/1000 TX RJ45 Type) b) The Switch should have at least a 4-Port 1/10 (dual rate) Gigabit Ethernet Interface of SFP+, LC connector, LX Type (to support Single Mode Fiber). The SFP+ transceiver should be supplied along with the switch. c) Should have a minimum of 2 GB RAM and 4 GB Flash. d) Should have the latest stable version of the Operating System. e) Throughput should support a minimum of 176 Gbps of non-blocking switching capacity and 130 Mpps of wire-speed forwarding rate architecture. f) Should support layer 3 (IPv4 and IPv6) functionality. g) Should support full BGP with default Routes from day one h) Should support both IPv4 and IPv6 feature set simultaneously (Including dual stack). i) Should be Rack mountable. j) Power Supply 220 ~ 240 Volt AC, 50 Hz input k) OEM should not have announced the “End of Sale”/ “End of Support” / “End of Life” for the proposed product. l) OEM should support the proposed product for at least 6 years from the date of Installation. m) Warranty of the proposed product should be for the period of 5 years from the date of Installation of the respective STPI Centre. n) Proposed product should be registered in “Trusted Telecom Portal” of DOT, documentary evidence/Declaration letter for the same shall be submitted. o) The proposed hardware or its operating system shall meet the relevant International Telecommunication Union or Telecommunication Engineering Centre (“TEC”) standards as per MTCTE or as specified by DoT dated 31.03.2015. The proposed hardware or its operating system shall also meet common criteria certification of EAL2/NDPP/Protection Profile or its equivalent or above for the proposed Products. A copy of the supporting documents shall be furnished. p) The proposed product should be capable of handling all the required features without performance degradation from day one. q) Should be populated with Redundant power supplies from day 1.
2	Interfaces

	a) The Switch should have at least a 48-Port Gigabit Ethernet Interface (10/100/1000 TX RJ45 Type) b) The Switch should have at least 4-Port 1/10 (dual rate) Gigabit Ethernet Interface of SFP+, LC connector, LX Type (to support Single Mode Fiber).
3	Performance
	a) Should have a minimum of 176 Gbps of non-blocking switching fabric or above. b) Should have a minimum of 130 Mpps wire-speed forwarding rate or above. c) Should support full BGP With Default Routes from day one d) The switch should support stacking from day 1 with stacking /MLAG throughput of a minimum 80 Gbps.
4	Layer-3 Features
	a) IPv4 and IPv6 b) Static Routing c) OSPF v2 and OSPF v3 (IPv6) d) Should support full BGP with Default Routes e) Dual stack supporting both IPv4 and IPv6 feature set simultaneously. f) Hardware and Software configuration of the Switch should support IPv6 from day one. g) The proposed product should have a permanent IPv6 license to support IPv6 features from day one. h) Port Channel/Ether Channel from day one
5	Layer-2 Features
	a) Should support IEEE 802.1Q VLAN Encapsulation b) Should support a minimum of 500 VLANs and 4,000 VLAN IDs. c) Should support Internet Group Management Protocol (IGMP) & Multicast Listener Discovery (MLD) Snooping. d) Should support Spanning-tree protocol. e) Should support Layer 2 ACLs f) Should support Link Aggregation Control Protocol (LACP) g) Should support Port trunking capability. h) Should support Port mirroring capability. i) The switch should be populated with Redundant power supplies from day-1
6	Security features
	a) AAA and RADIUS Authentication. b) Access-list support for both IPv4 & IPv6 and it should be able to log the access-list traffic for monitoring. c) SSH protocol version 2 and above.
7	Quality of Service (QoS) & Control
	a) Port-based and VLAN Based Rate limiting / Traffic shaping for Bandwidth allocation. b) Per port and VLAN bandwidth utilization monitoring through CLI and SNMP

8	Management
	a) Shall support SNMP v1/v2c/v3. b) Should support Link layer discovery protocol. c) Shall support management using CLI / GUI. d) Should support NTP. e) Should support packet capture mechanisms like sFlow/NetFlow. f) Manageability on Per Port Basis. g) Shall support FTP/TFTP. h) Should support NETCONF/YANG model.
9	Standards to be supported
	a) IEEE 802.1 D Spanning-Tree Protocol b) IEEE 802.1 w (Rapid Spanning Tree Protocol) c) IEEE 802.1 x (User Authentication) d) IEEE 802.3 ad/ IEEE 802.1AX (Link Aggregation) e) IEEE 802.3 x (Flow Control) f) IEEE 802.1Q (VLAN Encapsulation)

II. Layer-2 Switch	
1	Hardware Architecture / General Description
	a) The Switch should have at least a 24-Port Gigabit Ethernet Interface (10/100/1000 TX RJ45 Type) b) The Switch should have at least a 4-Port 1/10 (dual rate) Gigabit Ethernet Interface of SFP+, LC connector, LX Type (to support Single Mode Fiber). The SFP+ transceiver should be supplied along with the switch. c) Should have a minimum of 1 GB RAM and 4 GB Flash. d) Should have the latest stable version of the Operating System. e) Throughput should support (non-blocking) minimum of 128 Gbps switching capacity and 95Mpps of wire speed forwarding rate. f) Should support both IPv4 and IPv6 feature set simultaneously (Including dual stack). g) Should be Rack mountable. h) Power Supply 220 ~ 240 Volt AC, 50 Hz input i) OEM should not have announced the “End of Sale”/ “End of Support”, / “End of Life” for the proposed product. j) OEM should support the proposed product for at least 6 years from the date of Installation. k) Warranty of the proposed product should be for the period of 5 years from the date of Installation of the respective STPI Centre l) Proposed product should be registered in the “Trusted Telecom Portal” of DOT, documentary evidence/Declaration letter for the same shall be submitted. m) The proposed hardware or its operating system shall meet the relevant International Telecommunication Union or Telecommunication Engineering Centre (“TEC”) standards as per MTCTE or as specified by DoT dated 31.03.2015. The proposed hardware or its operating system shall also meet common criteria certification of EAL2/NDPP/MEF 3.0 or its equivalent or above for the proposed Products. A copy of the supporting documents shall be furnished. n) The proposed product should be capable of handling all the required features without performance degradation from day one.
2	Interfaces
	a) The Switch should have at least a 24-port Gigabit Ethernet Interface (10/100/1000 TX RJ45 Type) b) The Switch should have at least a 4-Port 1/10 (dual rate) Gigabit Ethernet Interface of SFP+, LC connector, LX Type (to support Single Mode Fiber).
3	Performance
	a) Should have a minimum of 128 Gbps of non-blocking switching fabric or above. b) Should have a minimum of 95 Mpps forwarding rate or above. c) The switch should support stacking from day 1 for stacking/MLAG throughput of a minimum of 60 Gbps.
4	Layer-2 Features

	a) Should support IEEE 802.1Q VLAN Encapsulation b) Should support a minimum of 500 VLANs and 4,000 VLAN IDs. c) Should support Internet Group Management Protocol (IGMP) & Multicast Listener Discovery (MLD) Snooping. d) Should support Spanning-tree protocol. e) Should support Layer 2 ACL's f) Should support Link Aggregation Control Protocol (LACP) g) Should support Port trunking capability. h) Should support Port mirroring capability.
5	Security features
	a) AAA and RADIUS Authentication. b) Access-list support for both IPv4 & IPv6 c) SSH protocol version 2 and above.
6	Quality of Service (QoS) & Control
	a) Per port and VLAN bandwidth utilization monitoring through CLI and SNMP.
7	Management
	a) Shall support SNMP v1/v2c/v3. b) Should support Link Layer Discovery Protocol. c) Shall support management using CLI / GUI. d) Should support NTP. e) Should support packet capture mechanisms like sFlow/NetFlow. f) Manageability on Per Port Basis. g) Shall support FTP/TFTP. h) Should support NETCONF/YANG model.
8	Standards to be supported
	a) IEEE 802.1 D Spanning-Tree Protocol b) IEEE 802.1 w (Rapid Spanning Tree Protocol) c) IEEE 802.1 x (User Authentication) d) IEEE 802.3ad/ IEEE 802.1AX (Link Aggregation) e) IEEE 802.3 x (Flow Control) f) IEEE 802.1Q (VLAN Encapsulation)

6. PART I-D: ANNEXURES AND FORMATS

Annexure-A: Bill of Material - Network Devices across STPI

S.No.	Particulars (As per the Technical Specification mentioned in the RFP document section Part I-C)	Qty
1.	48 Port Layer3 Switch with all accessories	75
2.	24 Port Layer2 Switch with all accessories	56
3.	Installation, Commissioning & Training	Lump sum
4.	Any additional Hardware / software required to meet the specification mentioned in Technical Specification in Part I-C	Lump sum
5.	Applicable taxes	

Directorate-wise Network Device requirement

S.No.	Directorate	Center Name	Address	Switch Layer-3	Switch Layer-2
1	Gurugram	Gurugram	Software Technology Parks of India 30, Electronic City, Phase IV, Udyog Vihar, Sector 18, Gurugram, Haryana 122015	1	6
2	Gurugram	Jaipur	Software Technology Parks of India, IT-21, EPIP, Sitapura Industrial Area, Jaipur (Rajasthan) - 302022	1	0
3	Gurugram	Jodhpur	Software Technology Parks of India, IT-21, EPIP, Sitapura Industrial Area, Jaipur (Rajasthan) - 302022	1	0
4	Guwahati	Guwahati	Software Technology Parks of India, Near L.G.B.I Airport, Borjhar, Guwahati - 781015 Assam	1	0
5	Guwahati	Agartala	Software Technology Parks of India, 2nd floor, Lichu Bagan Market Complex, Lichubagan, Agartala, Tripura	1	0
6	Guwahati	Gangtok	Software Technology Parks of India, NH-31A, Tadong, Gangtok, Sikkim 737102	1	0
7	Guwahati	Kohima	Software Technology Parks of India, Directorate of Information Technology & Communication, Thizama Road, Kohima, Nagaland - 797001	1	0
8	Guwahati	Shillong	Software Technology Parks of India,	1	0

			Short Round Road, East Khasi Hills, Lumjingshai, Shillong, Meghalaya 793001		
9	Hyderabad	Hyderabad	Software Technology Parks of India, 6Q3, 6th Floor, Cyber Towers, Hitech City, Madhapur, Hyderabad - 500081 Telengana	5	8
10	Hyderabad	Visakhapatnam	Software Technology Parks of India, Unit. No. 9, SDF-1 Building, Visakhapatnam Special Economic Zone, Near Duvvada Railway Station Visakhapatnam - 530049 Andhra Pradesh	0	2
11	Hyderabad	Vijayawada	Software Technology Parks of India, Beside Government Polytechnic College, Opp. Stella College, Near Benz Circle, R.S.No:7, Vijayawada - 520008 Andhra Pradesh	2	2
12	Hyderabad	Kakinada	Software Technology Parks of India, Collectorate Compound Kakinada - 533001 Andhra Pradesh	1	2
13	Hyderabad	Tirupati	Software Technology Parks of India, Survey No. 234, Behind Urban Haat, Tiruchanur Road Tirupati - 517503 Andhra Pradesh	1	2
14	Hyderabad	Warangal	Software Technology Parks of India, Kakatiya IT Park, H.No:2-5-906/1,2 Circuit House Road, Hanamkonda, Warangal – 506001	0	1
15	Kolkata	Kolkata	STPI IT Park, 6th Floor, Block-DP, Plot-5/1, at Sector-V, Salt Lake, Kolkata - 700091, West Bengal	1	0
16	Kolkata	Durgapur	Software Technology Parks of India Sahid Sukumar Banarjee Sarani, Opposite Spencer, Bidhannagar Dist: Paschim Bardhaman, Durgapur-713212	1	0
17	Kolkata	Siliguri	Software Technology Parks of India Plot No. JL 86, Matigara, Opposite Uttarayan, Dist: Darjeeling Siliguri-734010	1	0
18	Mohali	Mohali	Software Technology Parks of India Plot C-184, Industrial Area, Phase-8A, Sector 75, Mohali - 160071 Punjab	1	2
19	Mohali	Amritsar	Software Technology Parks of India, Amritsar, Plot A-9, Industrial Focal Point Extn-III, Amritsar	1	0
20	Mohali	Srinagar	Software Technology Parks of India 6-SIDCO, Electronics Complex, Old Airport Road, Rangreth, Srinagar, Kashmir, J&K- 191132	1	1
21	Mohali	Shimla	Software Technology Parks of India	4	0

			Block No-24,SDA Complex,Kasumpti, Shimla-171009 (H.P.)		
22	Noida	Noida	Software Technology Parks of India Ganga Shopping Complex, Sector-29, Noida - 201303 Uttar Pradesh	2	4
23	Noida	Dehradun	Software Technology Parks of India Plot No.IT-01, IT Park, IIE, Sahastradhara Road, Dehradun(Uttarakhand) - 248013	3	2
24	Noida	Lucknow	Software Technology Parks of India - Lucknow, STP Complex, Near Gomti Barrage, Gomti Nagar, Lucknow - 226010	1	1
25	Noida	Kanpur	Software Technology Parks of India - Kanpur, 8th floor, UPSIDA Complex, A-1/4 Lakhanpur, Kanpur- 208024, U.P.	1	0
26	Noida	Prayagraj	Software Technology Parks of India- Prayagraj, MNNIT Campus, Lucknow Road, Prayagraj (Uttar Pradesh)-211004	1	0
27	Noida	Meerut	Software Technology Parks of India - Noida, Ganga Software Technology Complex, (Uttar Pradesh) - 201303	1	1
28	Noida	Agra	Software Technology Parks of India, Agra, Sector-D, Shastripuram, Agra, Uttar Pradesh 282007	1	1
29	Patna	Patna	Software Technology Parks of India 13th Floor, Biscomaun Tower,Module-A5, West Gandhi Maidan, Patna-800001	1	1
30	Patna	Ranchi	Software Technology Parks of India Plot -8 Part, Namkum Industrial Area, Namkum Ranchi-834010	4	0
31	Patna	Darbhangha	Software Technology Parks of India, Darbhanga, Software Technology Parks of India Govt. Industrial Training Women ITI, Ramnagara, Darbhanga, Bahadurpur,Pin Code: 846001	1	0
32	Patna	Bhagalpur	Software Technology Parks of India, Bhagalpur, Software Technology Parks of India Backside of the Industrial Area (BIADA) Merrachak Road, Barari, Bhagalpur- 812001	1	0
33	Patna	Deoghar	Software Technology Parks of India Plot -NS.15 (Part), Industrial Area Jasidih , Deoghar- 814142	1	0
34	Patna	Dhanbad	Software Technology Parks of India, Dhanbad	1	0

35	Pune	Pune	Software Technology Parks of India Plot No.P-1, Rajiv Gandhi Infotech Park, MIDC, Hinjawadi, Pune - 411057 Maharashtra	3	2
36	Pune	Mumbai	Software Technology Parks of India 4th floor, Unit No. 4, Samruddhi Venture Park, MIDC Central Road, Andheri (East), Mumbai-400093	1	1
37	Pune	Nagpur	Software Technology Parks of India Plot No-3, IT Park, Parsodi, Near VRCE Telephone Exchange, Nagpur- 440022	0	1
38	Pune	Nashik	Software Technology Parks of India Plot No.IT-1, IT Park, Opp. S.D. Auto, MIDC, Ambad, Nashik- 422010	1	0
39	Pune	Chh. Sambhajnagar	Software Technology Parks of India Plot No-T-25, MIDC, Chikalthana, Chhatrapati Sambhajnagar-431210	1	0
40	Pune	Kolhapur	Software Technology Parks of India Behind Yalama Temple, Opp. Jai Prabha studio, IT Park, Kolhapur- 416012	1	0
41	Pune	Goa	Software Technology Parks of India 2nd Floor, Udyog Bhawan, Panaji, Goa-403001	1	0
42	Thiruvanantha puram	Thiruvananthap uram	STPI Building, Technopark Campus, Karyavttom, Thiruvananthapuram - 695581, Kerala	1	2
43	Thiruvanantha puram	Kochi	Software Technology Parks of India, KINFRA Hi-Tech Park, HMT Colony, Kalamassery, Kochi, Kerala - 683503	1	0
44	Bhopal	Bhopal	Software Technology Parks of India, Plot No C-11, IT Park, Near RGPV, New Jail Rd, Gandhi Nagar, Bhopal, Madhya Pradesh 462038	1	0
45	Bhopal	Indore	Software Technology Parks of India - Indore MPSEDC Building, Electronics Complex, Pardesipura, Indore (Madhya Pradesh) - 452010	1	1
46	Bhopal	Gwalior	Software Technology Parks of India - Gwalior, Morena Main Link Road, Ganga Malanpur Gwalior (Madhya Pradesh) - 474010	1	0
47	Bhopal	Bhilai	Software Technology Parks of India Mangal Bhawan, Nehru Nagar (East) Bhilai Chhattisgarh - 490020	1	0
48	Bhubaneswar	Bhubaneswar	Software Technology Parks of India ELITE Building, IDCO Plot No.2/A, Industrial Area, Gothapatna, Post -	2	4

			Malipada, District-Khurda, Bhubaneswar-751003		
49	Bhubaneswar	Rourkela	Software Technology Parks of India Near Pantha Niwas, Sector-5 Rourkela-769002, Odisha	0	1
50	Bhubaneswar	Berhampur	Software Technology Parks of India Plot-860/4562 (Near Income Tax Office) Ambapua, Berhampur-760 011	1	0
51	Bhubaneswar	Balasore	Software Technology Parks of India Balasore, IDCO Plot No. 2, Bampada Industrial Estate, Chhanpur, near Cipet College & NOCCI business Park, Balasore, Odisha 756056	1	0
52	Bengaluru	Bengaluru	Software Technology Parks of India No. 76, 77 & Part 78, 3rd Floor, Electronic City Phase - 1, Bengaluru - 560 100, Karnataka	2	0
53	Bengaluru	Hubballi	Software Technology Parks of India A Block,4th Floor, IT Park,Opposite Indira Glass House Hubballi-580029 Karnataka	1	0
54	Bengaluru	Mysuru	Software Technology Parks of India, 356-A, Hebbal Industrial Area, Mysuru – 570018 Karnataka	2	0
55	Bengaluru	Mangaluru	Software Technology Park of India, Blueberry Hill, Derebail Mangaluru - 575008 Karnataka	1	2
56	Chennai	Chennai	Software Technology Parks of India No. 5, III Floor, Rajiv Gandhi Salai, Taramani, Chennai - 600113 Tamilnadu	2	4
57	Chennai	Coimabto	Software Technology Parks of India 333/1, Ground Floor, Kumaraguru College of Technology, Chinnavedampatti, Coimbatore,Tamilnadu - 641 049	1	1
58	Chennai	Trichy	Software Technology Parks of India B-9, Light Engineering Shed, Trichy Regional Engg. College - Science & Technology Park (TREC-STEP), Trichy - 620 015	0	1
59	Gandhinagar	Gandhinagar	Software Technology Parks of India 9th Floor, GIFT One Tower, Block- 56, Road-5C, Zone-5, GIFT City, Gandhinagar-382 355 (Gujarat)	1	0
60	Gandhinagar	Surat	Software Technology Parks of India FP 27, TP 22, Jiav-Budia Road, Near Someswar Society, Vil: Bhestan, Tehsil: Chorasi, Surat - 395023 (Gujarat)	1	0
	Total			75	56

Annexure-B: Technical Compliance Sheet

The bidder must complete the Compliance Sheet below mentioning complied or not complied against every specification.

I. Layer3 Switch Compliance sheet

Sl. No	Description	(Complied/Not Complied)	Remarks
1	Hardware Architecture / General Description		
	a) The Switch should have at least a 48-Port Gigabit Ethernet Interface (10/100/1000 TX RJ45 Type)		
	b) The Switch should have at least a 4-Port 1/10 (Dual rate) Gigabit Ethernet Interface of SFP+, LC connector, LX Type (to support Single Mode Fiber). The SFP+ transceiver should be supplied along with the switch.		
	c) Should have a minimum of 2 GB RAM and 4 GB Flash.		
	d) Should have the latest stable version of the Operating System.		
	e) Throughput should support a minimum of 176 Gbps of non-blocking switching capacity and 130 Mpps of wire-speed forwarding rate architecture.		
	f) Should support layer 3 (IPv4 and IPv6) functionality.		
	g) Should support full BGP with default Routes from day one		
	h) Should support both IPv4 and IPv6 feature set simultaneously (Including dual stack).		
	i) Should be Rack mountable.		
	j) Power Supply 220 ~ 240 Volt AC, 50 Hz input		
	k) OEM should not have announced the "End of Sale"/ "End of Support" / "End of Life" for the proposed product.		
	l) OEM should support the proposed product for at least 6 years from the date of Installation.		
	m) Warranty of the proposed product should be for the period of 5 years from the date of Installation of the respective STPI Centre.		
	n) Proposed product should be registered in "Trusted Telecom Portal" of DOT,		

	documentary evidence/Declaration letter for the same shall be submitted.		
	o) The proposed hardware or its operating system shall meet the relevant International Telecommunication Union or Telecommunication Engineering Centre ("TEC") standards as per MTCTE or as specified by DoT dated 31.03.2015. The proposed hardware or its operating system shall also meet common criteria certification of EAL2/NDPP/Protection Profile or its equivalent or above for the proposed Products. A copy of the supporting documents shall be furnished.		
	p) The proposed product should be capable of handling all the required features without performance degradation from day one.		
	q) Should be populated with Redundant power supplies from day 1.		
2	Interfaces		
	a) The Switch should have at least a 48-Port Gigabit Ethernet Interface (10/100/1000 TX RJ45 Type)		
	b) The Switch should have at least 4-Port 1/10 (Dual rate) Gigabit Ethernet Interface of SFP+, LC connector, LX Type (to support Single Mode Fiber).		
3	Performance		
	a) Should have a minimum of 176 Gbps of non-blocking switching fabric or above.		
	b) Should have a minimum of 130 Mpps wire-speed forwarding rate or above.		
	c) Should support full BGP With Default Routes from day one		
	d) The switch should support stacking from day 1 with stacking /MLAG throughput of a minimum 80 Gbps.		
4	Layer-3 Features		
	a) IPv4 and IPv6		
	b) Static Routing		
	c) OSPF v2 and OSPF v3 (IPv6)		
	d) Should support full BGP with Default Routes		
	e) Dual stack supporting both IPv4 and IPv6 feature set simultaneously.		

	f) Hardware and Software configuration of the Switch should support for IPv6 from day one.		
	g) The proposed product should have a permanent IPv6 license to support IPv6 features from day one.		
	h) Port Channel/Ether Channel from day one		
5	Layer-2 Features		
	a) Should support IEEE 802.1Q VLAN Encapsulation		
	b) Should support a minimum of 500 VLANs and 4,000 VLAN IDs.		
	c) Should support Internet Group Management Protocol (IGMP) & Multicast Listener Discovery (MLD) Snooping.		
	d) Should support Spanning-tree protocol.		
	e) Should support Layer 2 ACLs		
	f) Should support Link Aggregation Control Protocol (LACP)		
	g) Should support Port trunking capability.		
	h) Should support Port mirroring capability.		
	i) The switch should be populated with Redundant power supplies from day 1.		
6	Security features		
	a) AAA and RADIUS Authentication.		
	b) Access-list support for both IPv4 & IPv6 and it should be able to log the access-list traffic for monitoring.		
	c) SSH protocol version 2 and above.		
7	Quality of Service (QoS) & Control		
	a) Port-based and VLAN Based Rate limiting / Traffic shaping for Bandwidth allocation.		
	b) Per port and VLAN bandwidth utilization monitoring through CLI and SNMP		
8	Management		
	a) Shall support SNMP v1/v2c/v3.		
	b) Should support Link layer discovery protocol.		
	c) Shall support management using CLI / GUI.		
	d) Should support NTP.		

	e) Should support packet capture mechanisms like sFlow/NetFlow.		
	f) Manageability on Per Port Basis.		
	g) Shall support FTP/TFTP.		
	h) Should support NETCONF/YANG model.		
9	Standards to be supported		
	a) IEEE 802.1 D Spanning-Tree Protocol		
	b) IEEE 802.1 w (Rapid Spanning Tree Protocol)		
	c) IEEE 802.1 x (User Authentication)		
	d) IEEE 802.3 ad/ IEEE 802.1AX (Link Aggregation)		
	e) IEEE 802.3 x (Flow Control)		
	f) IEEE 802.1Q (VLAN Encapsulation)		

II. Layer2 Switch Compliance sheet

Sl. No	Description	(Complied/Not Complied)	Remarks
1	Hardware Architecture / General Description		
	a) The Switch should have at least a 24-Port Gigabit Ethernet Interface (10/100/1000 TX RJ45 Type)		
	b) The Switch should have at least a 4-Port 1/10 (Dual rate) Gigabit Ethernet Interface of SFP+, LC connector, LX Type (to support Single Mode Fiber). The SFP+ transceiver should be supplied along with the switch.		
	c) Should have a minimum of 1 GB RAM and 4 GB Flash.		
	d) Should have the latest stable version of the Operating System.		
	e) Throughput should support (non-blocking) minimum of 128 Gbps switching capacity and 95Mpps of wire speed forwarding rate.		
	f) Should support both IPv4 and IPv6 feature set simultaneously (Including dual stack).		
	g) Should be Rack mountable.		
	h) Power Supply 220 ~ 240 Volt AC, 50 Hz input		
	i) OEM should not have announced the “End of Sale”/ “End of Support”, / “End of Life” for the proposed product.		
	j) OEM should support the proposed product for at least 6 years from the date of Installation.		

	k) Warranty of the proposed product should be for the period of 5 years from the date of Installation of the respective STPI Centre		
	l) Proposed product should be registered in the “Trusted Telecom Portal” of DOT, documentary evidence/Declaration letter for the same shall be submitted.		
	m) The proposed hardware or its operating system shall meet the relevant International Telecommunication Union or Telecommunication Engineering Centre (“TEC”) standards as per MTCTE or as specified by DoT dated 31.03.2015. The proposed hardware or its operating system shall also meet common criteria certification of EAL2/NDPP/MEF 3.0 or its equivalent or above for the proposed Products. A copy of the supporting documents shall be furnished.		
	n) The proposed product should be capable of handling all the required features without performance degradation from day one.		
2	Interfaces		
	a) The Switch should have at least a 24-port Gigabit Ethernet Interface (10/100/1000 TX RJ45 Type)		
	b) The Switch should have at least a 4-Port 1/10 (Dual rate) Gigabit Ethernet Interface of SFP+, LC connector, LX Type (to support Single Mode Fiber).		
3	Performance		
	a) Should have a minimum of 128 Gbps of non-blocking switching fabric or above.		
	b) Should have a minimum of 95 Mpps forwarding rate or above.		
	c) The switch should support stacking from day 1 for stacking/MLAG throughput of a minimum of 60 Gbps.		
4	Layer-2 Features		
	a) Should support IEEE 802.1Q VLAN Encapsulation		
	b) Should support a minimum of 500 VLANs and 4,000 VLAN IDs.		
	c) Should support Internet Group Management Protocol (IGMP) & Multicast Listener Discovery (MLD) Snooping.		
	d) Should support Spanning-tree protocol.		
	e) Should support Layer 2 ACL’s		

	f) Should support Link Aggregation Control Protocol (LACP)		
	g) Should support Port trunking capability.		
	h) Should support Port mirroring capability.		
5	Security features		
	a) AAA and RADIUS Authentication.		
	b) Access-list support for both IPv4 & IPv6		
	c) SSH protocol version 2 and above.		
6	Quality of Service (QoS) & Control		
	a) Per port and VLAN bandwidth utilization monitoring through CLI and SNMP.		
7	Management		
	a) Shall support SNMP v1/v2c/v3.		
	b) Should support Link Layer Discovery Protocol.		
	c) Shall support management using CLI / GUI.		
	d) Should support NTP.		
	e) Should support packet capture mechanisms like sFlow/NetFlow.		
	f) Manageability on Per Port Basis.		
	g) Shall support FTP/TFTP.		
	h) Should support NETCONF/YANG model.		
8	Standards to be supported		
	a) IEEE 802.1 D Spanning-Tree Protocol		
	b) IEEE 802.1 w (Rapid Spanning Tree Protocol)		
	c) IEEE 802.1 x (User Authentication)		
	d) IEEE 802.3ad/ 802.1ax (Link Aggregation)		
	e) IEEE 802.3 x (Flow Control)		
	f) IEEE 802.1Q (VLAN Encapsulation)		

(Signature of authorized signatory with seal & date)

Annexure-C: Components and Products

In Response to technical requirements bidders to required to fill-up the details of Component & Products in the following format:

SL. No.	Product Proposed (Model No)	Details (Individual Modules/ features/ Tech Capabilities etc)	Quantity	Brand name and Name of the OEM	List of Datasheet and brochures attached relevant to the proposed product

Note: Should be submitted along with Technical Bid.

(Signature of authorized signatory with seal & date)

Annexure-D: Training Requirements

Sl. No.	Topics to be Covered	Remarks
1	Proposed Product Knowledge - Architecture of Product - Operating System Details - Others	Theory
2	Basic Management: - Equipment Handling procedures - Mode of Access (SSH, Console, GUI) - Basic Commands - Trouble Shooting	Theory & Lab
3	Configuration Management: - BGP, OSPF, MPLS, VOIP both IPv4 and IPv6. - Link Aggregation, VLAN, ACL's both IPv4 and IPv6 - Port Based & VLAN Based Bandwidth allocation - Traffic Classification & Prioritization	Theory & Lab
4	System Management: - Backup & Restore of Operating System - Backup & Restore of Configuration - AAA - NTP, SNMP.	Theory & Lab

Note: Should be submitted along with Technical Bid.

(Signature of authorized signatory with seal & date)

Annexure-E: Check List

SI No.	Description	Compliance
1	EMD details	Submitted / Not Submitted
2	Copy of certificate authorized by OEM and MAF	Submitted / Not Submitted
3	Copy of Certificate issued by TEC / DOT/ common criteria certification of EAL2/NDPP/MEF 3.0 or its equivalent or above for the proposed Products	Submitted / Not Submitted
4	Audited financial Statement for past 3 financial years	Submitted / Not Submitted
5	IT returns for past 3 financial years	Submitted / Not Submitted
6	Purchase Order copies, invoices and completion certificate for the past 3 years	Submitted / Not Submitted
7	Copy of the PAN Card	Submitted / Not Submitted
8	Copy of GST	Submitted / Not Submitted
9	Copy of Registration (RoC),/ Incorporation of the firm/company, MSME Registration Certificate (if applicable)	Submitted / Not Submitted
10	Technical Compliance Sheet as per Annexure-B	Submitted / Not Submitted
11	Components & Products details as per Annexure-C	Submitted / Not Submitted
12	Acceptance to training terms as per Annexure-D	Submitted / Not Submitted
13	Submission of Checklist as per Annexure-E	Submitted / Not Submitted
14	Tender Acceptance letter as per Annexure-F	Submitted / Not Submitted
15	Declaration for non-debarment & non-blacklisting as per format Annexure-G	Submitted / Not Submitted
16	Acceptance to submit NDA as per Annexure -H in part I-D	Submitted / Not Submitted
17	Certificate of Conformity/ No Deviation. Compliance needs to be provided on letter head as per format at Annexure -I	Submitted / Not Submitted
18	Board Resolution or Power of Attorney for the Authorized Signatory shall be submitted as per as per format at Annexure -J.	Submitted / Not Submitted
19	Copy of EMD Transaction (NEFT/RTGS) details /EMD Exemption certificates with Bid security Declaration as per format at Annexure -K.	Submitted / Not Submitted
20	Acceptance to the Scope of works as per bid document at Part I-B. Self-attested and signed scope of works document to be submitted.	Submitted / Not Submitted
21	Acceptance to the payment terms, penalty and liquidated damages (LD) as per the bid document at Part I-B.	Submitted / Not Submitted
22	Bid validity for 180 days after the date of opening of bid	Submitted / Not Submitted

23	Documentary evidence for having support center at least 4 major cities across India along with trouble call escalation matrix.	Submitted / Not Submitted
24	Acceptance to warranty terms (5 years) and service norms as per RFP	Complied / Not Complied
25	Declaration from OEM w.r.t product warranty, End of Life, End of Support etc as per RFP terms.	Submitted / Not Submitted
26	Product datasheets and brochures	Submitted / Not Submitted
27	Uploaded BoQ as per format in XLS	Submitted / Not Submitted
28	Acceptance to Support Norms - OEM should support the proposed product for at least 6 years from the date of delivery	Submitted / Not Submitted
29	Proposed product should be registered in "Trusted Telecom Portal" of DOT, documentary evidence/Declaration letter for the same shall be submitted.	Submitted / Not Submitted

Note: Should be submitted along with Technical Bid.

(Signature of authorized signatory with seal & date)

Annexure-F: Tender Acceptance Letter

(To be submitted duly signed format (Scanned Copy) by the authorized signatory on Company Letter Head)

Date:.....

To,
Software Technology Parks of India
1st Floor, Plate B, Office Block-1,
East Kidwai Nagar, New Delhi - 110023

Sub: Acceptance in respect of Terms & Conditions of Tender document for Supply, Installation, Testing, Commissioning and training of Network Devices - LAYER-3 Switches and Layer-2 Switches at various STPI Directorates as mentioned in the Annexure-A.

Sir,

1. I/We have downloaded/ obtained the tender document(s) for the above mentioned 'Tender/Work' from the web site <https://gem.gov.in>.
2. I/We hereby certify that I/we have read all the terms and conditions of tender document from Page No. _____ to _____ (including all Annexure(s)/Para's, etc., which shall form part of the contract agreement, and I/we shall abide hereby by all the terms & conditions contained therein.
3. The corrigendum(s) issued from time to time by your department/organization too has also been taken into consideration, while submitting this acceptance letter.
4. I/ We hereby unconditionally accept all the terms and conditions of above-mentioned tender document and corrigendum(s) as applicable.
5. In case any provisions of this tender are found violated, then your department/organization shall without prejudice to any other right or remedy be at liberty to reject my bid including the forfeiture of earnest money deposit.
6. I/ We confirm that our bid shall be valid up to **180** days from the date of opening of Bid.
7. I/ We hereby certify that all the statements made, and information supplied in the enclosed Annexures/Para's etc. furnished herewith are true and correct.
8. I/ We have furnished all the information and details necessary for demonstrating our qualification and have no further prominent information to supply.
9. I/ We understand that you are not bound to accept the lowest or any bid you may receive.
10. I/ We certify / confirm that we comply with the eligibility requirements as per Bid documents.

Seal and Sign of Bidder

Name:

Address:

Annexure-G: DECLARATION FOR NON-DEBARMENT & NON-BLACKLISTING

This is to certify that << COMPANY NAME >> has not been blacklisted by any Central /State Government (incl. its department/agency) or was declared ineligible by the Government of India/State/UT Government for corrupt and fraudulent practices as on 31st March 2022.

I hereby certify that the information furnished in the RFP Ref No..... dated..... 2025 is full and correct to the best of my/our knowledge. I understand that in case any deviation is found in the statement at any stage, the bid will summarily be rejected and the bidder will be liable to be blacklisted and will not be permitted to have any dealing with the STPI in future.

**Seal and Sign of Bidder
Name & Address:**

Annexure-H: NON-DISCLOSURE AGREEMENT

Date.....

THIS AGREEMENT is valid till six years from the date of work order, and is made by and between **SOFTWARE TECHNOLOGY PARKS OF INDIA**, an Society under Ministry of Electronics and Information Technology, Govt. of India herein referred to as '**DISCLOSING PARTY**' whose address is **1st Floor, Plate B, Office Block-1, East Kidwai Nagar, New Delhi – 110023** and **M/s.**

Both the parties shall mean and include their successors at Office from time to time, legal representatives, administrators, executors and assigns, etc.

This agreement shall govern the conditions of disclosure by disclosing party to Recipient of certain confidential and proprietary information that is oral, written, or in computer file format. Examples of Confidential Information include the identities of companies, consultants and other service providers used by disclosing party, both foreign and domestic, in connection with disclosing party's business, supplier lists, supplier information, computer databases containing customer, product and vendor information, designs, drawings, specifications, techniques, models, documentation, diagrams, flow charts, research and development process and procedures, 'know-how', new product or new technology information, financial, marketing and sales information and projections, product pricing, profitability, marketing techniques and materials, marketing timetables, strategies and development plans, trade names and trademarks not yet disclosed to the public, business methods and trade secrets, and personnel information.

1. Purpose of Disclosure. Disclosing party is disclosing the Confidential Information to Recipient in order for Recipient to evaluate the possibility of using disclosing party's services like Call Centers/Contact Centers Projects, Business Process Outsourcing covering all different kind of Verticals, Information Technology Services, Back and Transaction Processing Services, Business Analysis, Business Process Re-engineering, Data Analysis, Quality Analysis and the Statutory & Datacom services etc.
2. Confidentiality Obligations of Recipient. Recipient hereby agrees:
 - (a) Recipient will hold the Confidential Information in complete confidence and not to disclose the Confidential Information to any other person or entity, or otherwise transfer, publish, reveal, or permit access to the Confidential Information without the express prior written consent of Disclosing Party.
 - (b) Recipient will not copy, photograph, modify, disassemble, reverse engineer, decompile, or in any other manner reproduce the Confidential Information without the express prior written consent of disclosing party.

If any Confidential Information is delivered to Recipient in physical form, such as data files or hard copies, recipient will return the Confidential Information, together with any copies thereof, promptly after the purpose for which they were furnished has been accomplished, or upon the request of disclosing party. In addition upon request off disclosing party in writing/email Recipient will destroy materials prepared by Recipient that contain Confidential Information.

- (c) Recipient shall use Confidential Information only for the purpose of evaluating Recipient's interest in using disclosing party's services, and for no other purpose. Without limiting the generality of the previous sentence, Recipient specifically agrees not to sell, rent, or otherwise disclose any of disclosing party's Confidential Information either in full or part to any competitor of disclosing party, nor will Recipient use the Confidential Information to directly or indirectly contact or contract with any of disclosing party's employees, vendors, contractors and agents who carry out or otherwise fulfill the services on behalf of disclosing party (its 'Affiliates'). Recipient shall promptly notify disclosing party of any disclosure or use of Confidential Information in violation of this Agreement for which disclosing party shall indemnify the Recipient for that part.
3. Exclusions. None of the following shall be considered to be 'Confidential Information':
- (a) Information which was in the lawful and unrestricted possession of Recipient prior to its disclosure by disclosing party;
 - (b) Information which is readily ascertainable from sources of information freely/easily available in the general public;
 - (c) Information which is obtained by Recipient from a third party who did not derive such information from disclosing party.
4. Remedies. Recipient acknowledges that disclosing party's Confidential Information has been developed or obtained by the investment of significant time, effort and expense and provides disclosing party with a significant competitive advantage in its business, and that if Recipient breaches its obligations hereunder, disclosing party will suffer immediate, irreparable harm for which monetary damages will provide inadequate compensation. Accordingly, the disclosing party will be entitled, in addition to any other remedies available at law in equity, to injunctive relief to specifically enforce the terms of this Agreement. Recipient agrees to indemnify disclosing party against any losses sustained by disclosing party, including reasonable attorney's fees, by reason of the breach of any provision of this Agreement by Recipient. Recipient further acknowledges that disclosing party's business would be severely hurt if Recipient were to directly contract with its Affiliates without the participation of disclosing party. Therefore, if Recipient directly or indirectly contracts with any of disclosing party's Affiliates whose identity and/or particulars are disclosed to Recipient pursuant to this Agreement

(Except Affiliates with whom Recipient had a demonstrable prior existing business relationship). In the event of circumvention, by the Recipient whether directly or indirectly, the disclosing party shall be entitled to a legal monetary penalty award, equal to the maximum consulting service/consulting fee, commission/profit originally expected or contemplated to be realized from such transaction(s). This payment levied against and paid immediately by the party engaged in circumvention and also in addition includes all legal expenses in the recovery of these funds if collected through legal action by either party. This penalty shall not apply when the alleged Circumventure does not result in a transaction being concluded. The parties acknowledge it would be extremely difficult or impossible to accurately it would be extremely difficult or impossible to accurately fix the actual damages that disclosing party would suffer in the event of a breach of the aforementioned obligations, and that the liquidated damages provided for herein are a reasonable estimate of

disclosing party's actual damages, which shall be fixed by the arbitrator who shall also be in the same business.

5. No Rights Granted to Recipient. Recipient further acknowledges and agrees that the furnishing of Confidential Information to Recipient by disclosing party shall not constitute any grant or license to Recipient under any legal rights now or hereinafter held by disclosing party.
6. Miscellaneous Provisions:
 - (a) This Agreement sets forth the entire understanding and Agreement between the parties with respect to the subject matter hereof and supersedes all other oral or written representations and understanding. This Agreement may only be amended or modified by a writing signed by both parties.
 - (b) If any provision of the Agreement is held to be illegal, invalid or unenforceable, the legality, validity and enforceability of the remaining provisions will not be affected or impaired.
 - (c) This Agreement is binding upon the successors, assigns and legal representatives the parties hereto, and is intended to protect Confidential Information of any successors or assign of disclosing party.
 - (d) Each Provision of this Agreement is intended to be valid and enforceable to the fullest extent permitted by law. If any provision of this Agreement is determined by any court of competent jurisdiction or arbitrator to be invalid, illegal, or enforceable to any extent, that provision shall, if possible, be construed as though more narrowly drawn, if a narrower construction would avoid such invalidity, illegality, or unenforceability, be served, and the remaining provisions of this Agreement shall remain in effect/force.
 - (e) The terms and conditions governing the provision of the agreement shall be governed by and construed in accordance with laws of the union of India and shall be subject to the exclusive Jurisdiction of the courts of New Delhi.
 1. Any or all disputes arising out or in connection with this agreement shall so far as may be possible to settled amicably between the parties within a period of thirty days from such dispute(s) arising.
 2. However failing such amicable settlement all disputes and differences out of the construction of or concerning anything contained in or arising out of or in connection with this agreement as to the rights, duties or liabilities arising it, to the parties shall be referred to a panel of three arbitrators, for conducting Arbitration in accordance with the provisions of Arbitrations and Conciliation Act 1996 and its all amendment.
 3. It is agreed that each party shall appoint one arbitrator and the third arbitrator from the same business.
 4. The appointment of arbitrators shall be done within a period of three months from the date of receipt of notice from the aggrieved party requesting to refer the matter to arbitration in case amicable settlement fails.
 5. The parties shall mutually ensure and co-operate with each other in the arbitral proceedings, so that the same can be concluded and awarded within a period of six months from the date of commencement of the arbitral proceedings.
 6. The arbitral proceedings shall be conducted in English, both parties shall be bound by the award passed and delivered by the arbitral tribunal and shall not

attempt to challenge the authenticity of the award, before any authority or courts or any other statutory body.

7. The venue of arbitration shall be Delhi.

- (f) If any litigation is brought by either party regarding the interpretation or enforcement of this Agreement, the prevailing party will recover from the other all costs, attorney's fees and other expenses incurred by the prevailing party from the other party.

Signed on behalf of
M/s Software Technology Parks of India

Signed on behalf of
M/s.

Signature:
Name:
Designation with seal:

Signature:
Name:
Designation with seal:

Date:

Date:

Annexure-I: CERTIFICATE OF CONFORMITY/ NO DEVIATION

{to be filled by the bidder}

To,
The Director
STPI

This is to certify that, our Technical bid is in conformity to the entire scope of work/ services and Terms & Conditions mentioned in RFP, and which I/ We shall supply if I/ We am/ are awarded with the work, are in conformity with the scope of work of the bidding document and that there are no deviations of any kind from the scope of work/services.

Also, I/ we have thoroughly read the tender/ bidding document and by signing this certificate, we hereby submit our token of acceptance to all the tender terms & conditions of the bidding document without any deviations.

I/ We also certify that the price I/ we have quoted is inclusive of all the cost factors involved in the execution of the scope of services as mentioned in the RFP, to meet the desired Standards set out in the Tender/ bidding Document.

Thanking you,

Name of the Bidder: -
Authorised Signatory: -
Seal of the Organization: -
Date:
Place:

Annexure-J: BIDDER'S AUTHORIZATION CERTIFICATE

{to be filled by the bidder}

To,
The Director
STPI

I/ We {Name/ Designation} hereby declare/ certify that {Name/ Designation} is hereby authorized to sign relevant documents on behalf of the company/ firm in dealing with Tender reference No. STPI/ dated __. He/ She is also authorized to attend meetings & submit technical & commercial information/ clarifications as may be required by you in the course of processing the Bid. For the purpose of validation, his/ her verified signatures are as under.

Thanking you,

Name of the Bidder: -
Authorised Signatory: -
Seal of the Organization: -
Date: _____
Place: _____

Verified Signature:

Please attach the board resolution / valid power of attorney in favour of person signing this authorizing letter.

Annexure-K: BID SECURITY DECLARATION

(To be filled by the bidder On Bidders Letter head)

Date: _____ Tender No. _____

To,
The Director
STPI

I/We. The undersigned, declare that:

I/We understand that, according to your conditions, bids must be supported by a Bid Securing Declaration.

I/We accept that I/We may be disqualified from bidding for any contract with you for a period of Two Year as per GFR 151 (iii) from the date of notification if I am /We are in a breach of any obligation under the bid conditions, because I/We

- a) have withdrawn/modified/amended, impairs or derogates from the tender, my/our Bid during the period of bid validity specified in the form of Bid; or
- b) having been notified of the acceptance of our Bid by the purchaser during the period of bid validity (i) fail or reuse to execute the contract, if required, or (ii) fail or refuse to furnish the Performance Security/ PBG, in accordance with the Instructions to Bidders.

I/We understand this Bid Securing Declaration shall cease to be valid if I am/we are not the successful Bidder, upon the earlier of (i) the receipt of your notification of the name of the successful Bidder; or (ii) thirty days after the expiration of the validity of my/our Bid.

Signed: _____ (insert signature of person whose name and capacity are shown)
in the capacity of _____ (insert legal capacity of person signing the Bid Securing Declaration)

Name: (insert complete name of person signing he Bid Securing Declaration)

Duly authorized to sign the bid for an on behalf of (insert complete name of Bidder)

Dated on _____ day of _____ (insert date of signing)

Corporate Seal (where appropriate)

Annexure-L: Format for performance Bank Guarantee (PBG)

1. In consideration of the Software Technology Parks of India (hereinafter called "STPI") having agreed to allow M/s (Hereinafter called "the said Vendor/Successful bidder") from the demand under the terms and conditions of RFP Ref No: dated along with its all corrigendum/addendums for the hereinafter called "the said Agreement" for furnishing Performance Bond for the due fulfilment by the said Vendor of the terms and conditions in the said Agreement, by production of a BANK GUARANTEE for Indian Rs. (Indian Rsonly). We the (Name of the Bank) having our Head Office at and having branch atreferred to as "the Bank" at the request of M/s. Successful Bidder(s) do hereby undertake to pay to STPI an amount not exceeding Indian Rs..... (Indian Rs..... only).
2. We (Name of the Bank) branch do hereby undertake to pay the amounts due and payable under this guarantee without and demure, merely on a demand from STPI stating that the amount claimed is required to meet the recoveries due or likely to be due from the said Successful Bidder(s). Any such demand made on the Bank shall be conclusive as regards the amount due and payable by the Bank under this guarantee. However, our liability under this guarantee shall be restricted to an amount not exceeding Rs (Rs only).
3. We undertake to pay to the STPI, the amount due under this Guarantee so demanded notwithstanding any dispute to disputes raised by the Successful Bidder(s) in any suit or proceeding pending before any Court or Tribunal relating thereto, our liability under this present being absolute and unequivocal.
4. The payment so made by us under this bond shall be a valid discharge of our liability for payment thereunder.
5. We (Name of the Bank) branch further agree that the guarantee herein contained shall remain in full force and effect during the period that would be taken for the performance of the said agreement and that it shall continue to be enforceable till the dues of STPI under or by virtue of the said agreement have been fully paid and its claims satisfied or discharged or till the Project Coordinator on behalf of STPI certifies that the terms and conditions of the said Agreement have been fully and properly carried out by the said Successful Bidder(s) accordingly discharges this guarantee.
6. We (Name of the Bank) branch further agree with STPI, that STPI shall have the fullest liberty without our consent and without affecting in any manner our obligations hereunder to vary any of the terms and conditions of the said Agreement or to extend time of performance by the said Successful Bidder(s) from time to time or to postpone for any time or from time to time any of the powers exercisable by STPI against the said Successful Bidder(s) and to forbear or enforce any of terms and conditions relating to the said agreement and we shall not be relieved from our liability by reason of any such variation or extension being granted to the said Successful Bidder(s) or for any forbearance act or omission on the part of the STPI or any indulgence by the STPI to the said Successful Bidder(s) or by any such matter or thing whatsoever which under the law relating to sureties would but for this provision have effect of so relieving us.
7. This guarantee will not be discharged due to the change in the constitution of the Bank or the Successful Bidder(s).
8. We hereby waive the necessity of your demanding the Successful Bidder before presenting us with the demand.

9. We (Name of the Bank) Branch lastly undertake not to revoke this guarantee except with the previous consent of the STPI in writing.

10. This guarantee shall be valid upto unless extended on demand by STPI. Notwithstanding anything contained herein before our liability against this guarantee is restricted to Indian Rs. (Indian Rs..... only) and it will remain in force till unless a claim or demand in writing is made against us under this guarantee before the expiry of six months from the aforesaid date that is beforeof(.....) all your rights under the said guarantee shall be forfeited and we shall be relieved and discharged from all liability hereunder.

Dated the day of for (Name of the Bank)Branch.

WITNESS 1

WITNESS 2

(Signature)

(Signature)

Attorney as per Power of Attorney :

Attorney Number & Date :

Part-II: Annexure-BOQ

Sl. No.	Item Description	Item Code / Make	Quantity	Units	Unit Rate in INR	Total Amount in INR
1.	LAYER-3 Switches with all accessories including Installation, Commissioning, training & Any additional Hardware / software required to meet the specification mentioned in Technical Specification in Part I-C		75	Nos		
2.	LAYER-2 Switches with all accessories including Installation, Commissioning, training & Any additional Hardware / software required to meet the specification mentioned in Technical Specification in Part I-C		56	Nos		
Total						
Applicable Taxes						
Grand Total						